

Electronic Patent Application Fee Transmittal

Application Number:	10789914			
Filing Date:	27-Feb-2004			
Title of Invention:		RESIN COMPOSITION, PREPREG, LAMINATE, AND SEMICONDUCTOR PACKAGE		
First Named Inventor/Applicant Name:	Takeshi Hosomi			
Filer:	Robert M. Siminski/janice ogg			
Attorney Docket Number:	2497-000002/CP			
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Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Priority accept. unintent. delayed claim	1454	1	1410	1410
Patent-Appeals-and-Interference:				
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Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Total in USD (\$)				1410